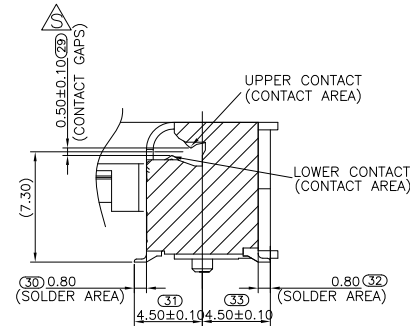


REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2015/11/02	Phebe Su



76.00 MAX (LATCH OPEN)

68.10±0.25 (SLOT LENGTH)

41.95±0.15

23.95±0.15

41.65±0.1

23.65±0.1

0.6x65=39

0.6x35=21

0.15±0.03 204PLC

0.10 Z

0.6 TYP.

PIN203

DDR3L RVS

1.5V

PIN204

SEE A

DATE CODE

1.65

3

64.7REF

71.1MAX.

72.70MAX.

74±0.1

1.40

3

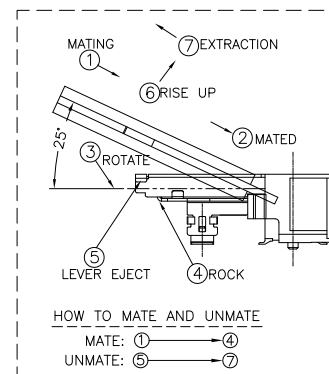
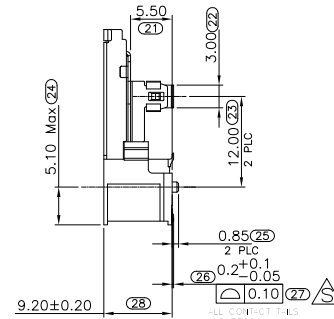
3.70

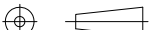
3.70

CL OF TWO POST

PIN1

PIN2



NO	VARIETY	QTY	METERIAL	REMARK	
 Matrix Electronics Co.,Ltd					
TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 9.2H RVS ASSY	
		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO.	MDDR3-204XX13
		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO.	NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE : 2015/11/02	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	1 OF 2

[illegible]

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2015/11/02	Phebe Su

0.15 MAX.

NOTE:

1. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAIZATION.
3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER Ni PLATING 0.002MIN.
4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE.
5. BORDER OF COMPONENT AREA.
6. REFER TO JEDEC SPEC. MO-268 FOR COMPLETE MODULE.

0.15 MAX.

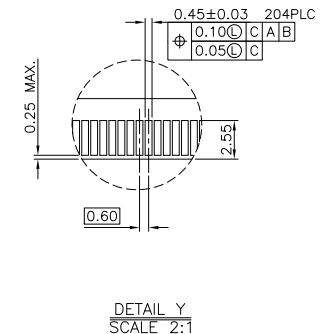
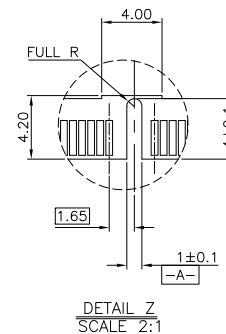
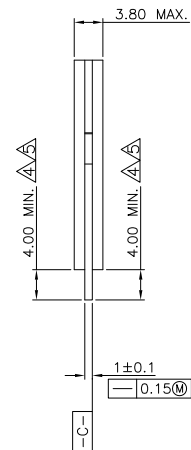
DETAIL Z
SCALE 2:1

DETAIL Y
SCALE 2:1

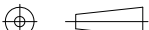
30.00	CA
31.75	BA
25.40	AA
DIM. A	SDRAM VARIATIONS

NO	VARIETY	QTY	METERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY :	DATE :	PART NAME:
		Phebe Su	2015/11/02	DDR3 SO DIMM 9.2H RVS ASSY
		CHECKED BY:	DATE :	PART NO.
		Vicky Hsieh	2015/11/02	MDDR3-204XX13
		APPROVED BY1:	DATE :	MOLD NO.
		Richard Hsieh	2015/11/02	NA
		APPROVED BY2:	DATE :	DRAW NO.
		Richard Hsieh	2015/11/02	SHEET NO.
				2 OF 2

1. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAZATION.
3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER Ni PLATING 0.002MIN.
4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE. PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
5. BORDER OF COMPONENT AREA.
6. REFER TO JEDEC SPEC. MO-268 FOR COMPLETE MODULE.



30.00	CA
31.75	BA
25.40	AA
DIM. A	SDRAM VARIATIONS

NO	VARIETY	QTY	MATERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X.X ±0.25 X.XX ±0.15 X.XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 9.2H RVS ASSY
		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO. MDDR3-204XX13
		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO. NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE :	DRAW NO.
SCALE:1:1	SIZE:A4	Richard Hsieh	2015/11/02	SHEET NO. 2 OF 2